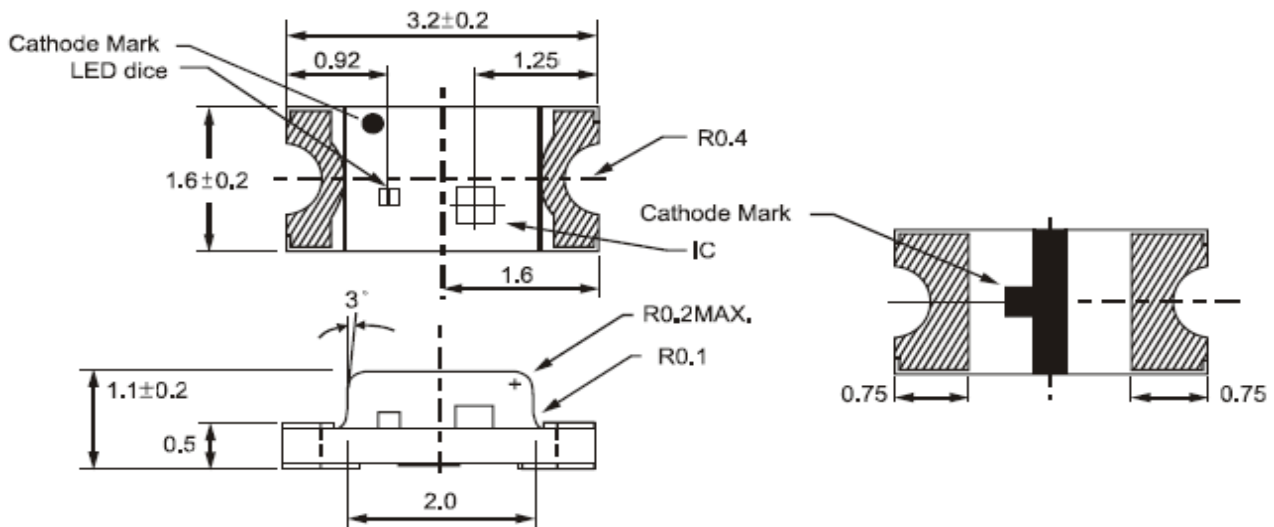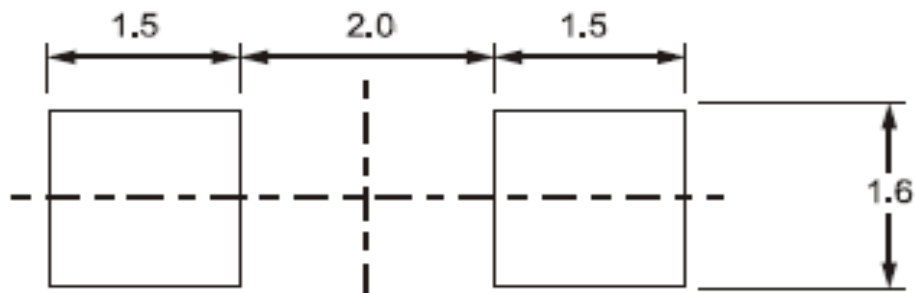**EDCON COMPONENTS**
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Applications

- Interior automotive lighting
- Optical indicators
- Communication Products
- Backlighting
- Toys

Technical Drawing

Recommended Soldering Pattern

Notes :
All dimensions in mm tolerance is
± 0.1mm unless otherwise noted.

SMT Blinking Chip LED		
Green		
Part No.:	**M11N6004**	
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Absolute Maximum Ratings

Ta=25°C

Item	Symbol	GaP	Unit
Power Dissipation	P_D	---	mW
DC Forward Current	I_F	12	mA
Plused Forward Current	I_{FP}*	100	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{OP}	-25 to 80	°C
Storage Temperature	T_{ST}	-20 to 85	°C

* 0.1 msec pulse, 10% duty cycle

Electrcal / Optical Characteristics

Ta=25°C

Ermitting Color		Green	
Material		GaP	
Forward Current	typ.	20	A
	max.	---	A
Wavelength typ.	λP	557	nm
	Δλ	---	nm
Color Temperature	min.	---	K
	max.	---	K
Luminous Intensity *	min.	1.6	mcd
	typ.	3.0	mcd
Pulse Rate VDD = 5V	min.	2.0	Hz
	typ.	2.4	Hz
	max.	3.0	Hz
Reverse Current	max.	---	μA
Viewing Angle	2Θ1/2	120	

* Per NIST standards

SMT Blinking Chip LED
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Curvs
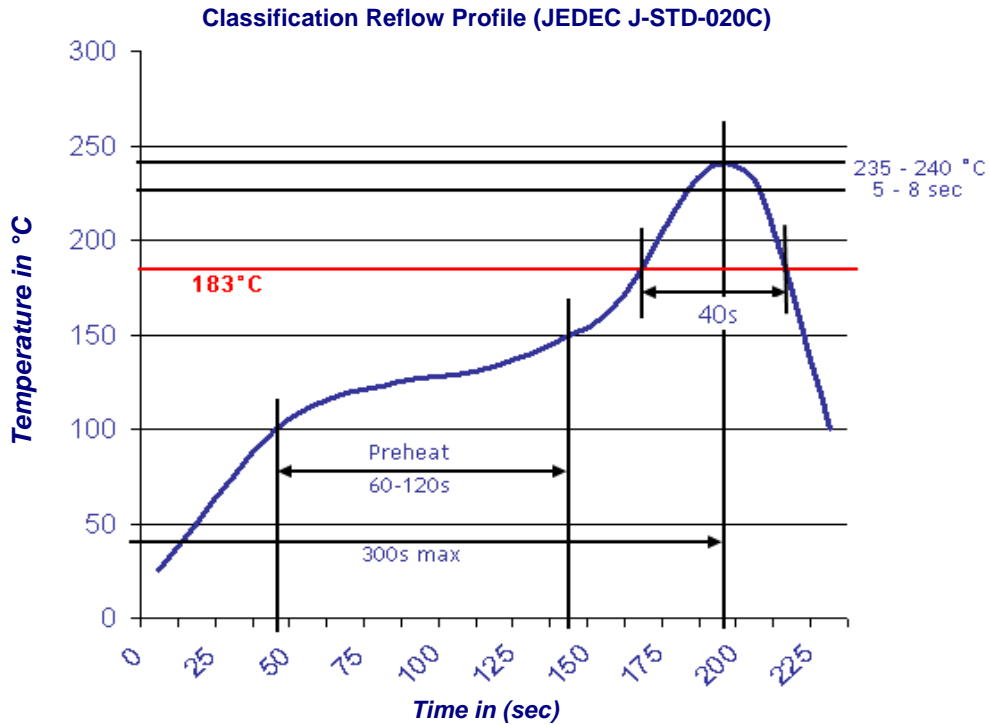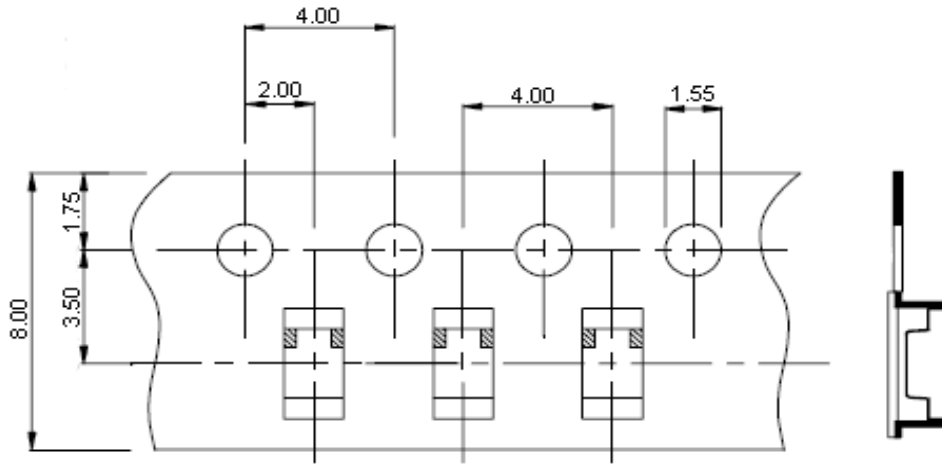
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Green</td></tr>
<tr></tr>
<tr><td>Part No.:</td><td>M11N6004</td></tr>
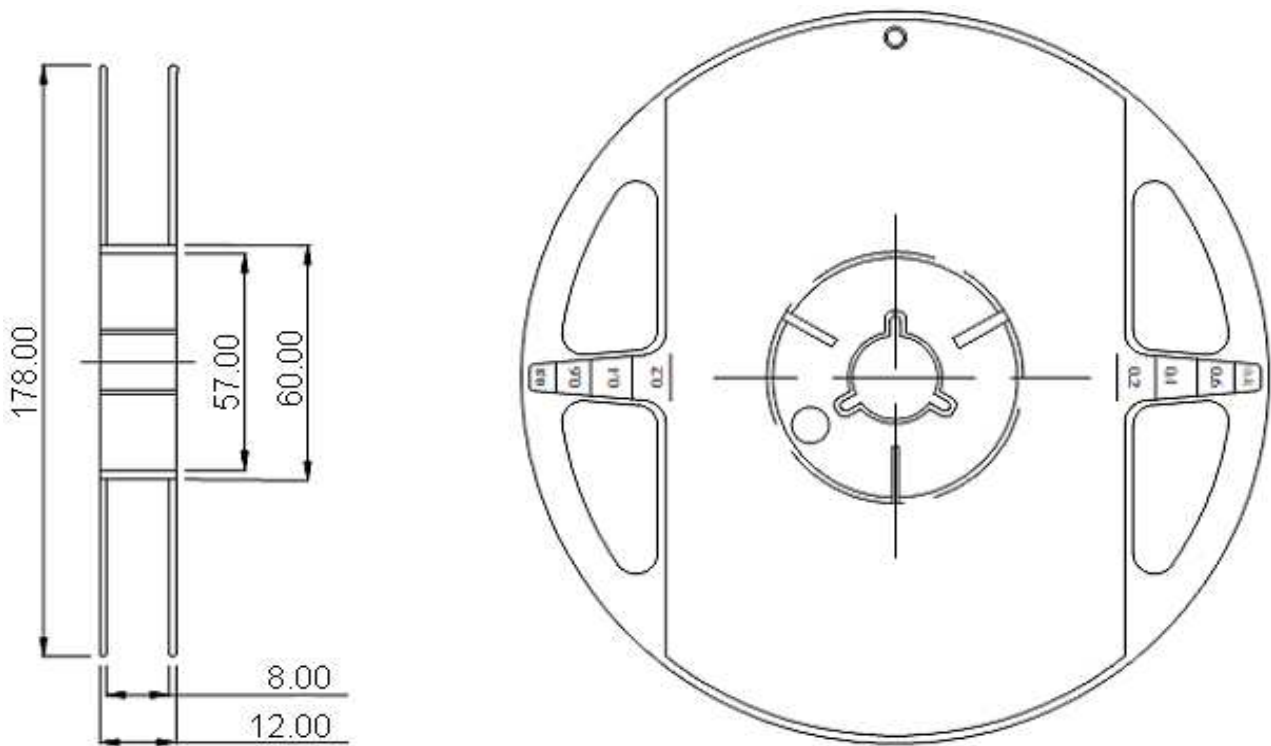<tr><td>Customer:</td><td></td></tr>
</table>

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Solder Condition

Lead Free Solder

Classification Reflow Profile (JEDEC J-STD-020C)

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Packing Specifications

Reel Specifications

	SMT Blinking Chip LED *Green*					
Part No.:			**M11N6004**			
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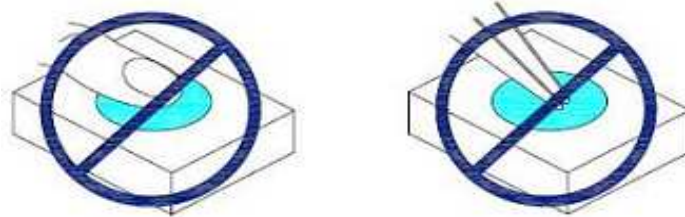| DRW:	Dong	CHKD	Chang	MATL:	Chui	DATE	05.12.2009
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Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible.
Although ist characteristic significantly reduces thermal stress, it is more susceptible
to damage by external mechanical force. As a result, special handling precautions need
to be observed during assembly using silicone encapsulated LED products. Failure
to comply might leads to damage and premature failure of th LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools

2. Do not directly touch or handle the silicone lens surfance. It may damage the
   internal circuitry.

3. Do not stack together assembled PCBs containing exposed LEDs. Outside impact
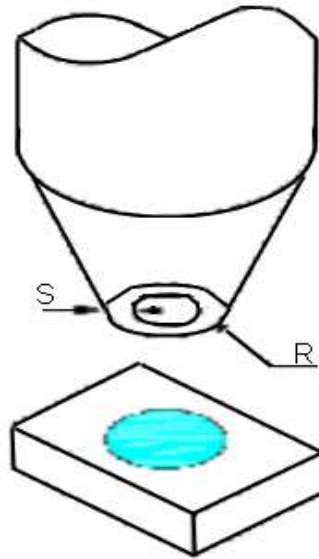   may scratch the silicone lens or damage the internal circuitry.

				SMT Blinking Chip LED *Green*		
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4. The outer diameter of the TOP LED pickup nozzle should not exceed the size of the
   LED to prevent air leaks. The inner diameter of the nozzle should be as large
   as possible.

5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the
   LED surface during pickup.

6. The dimensions of the component must be accurately programmed in the
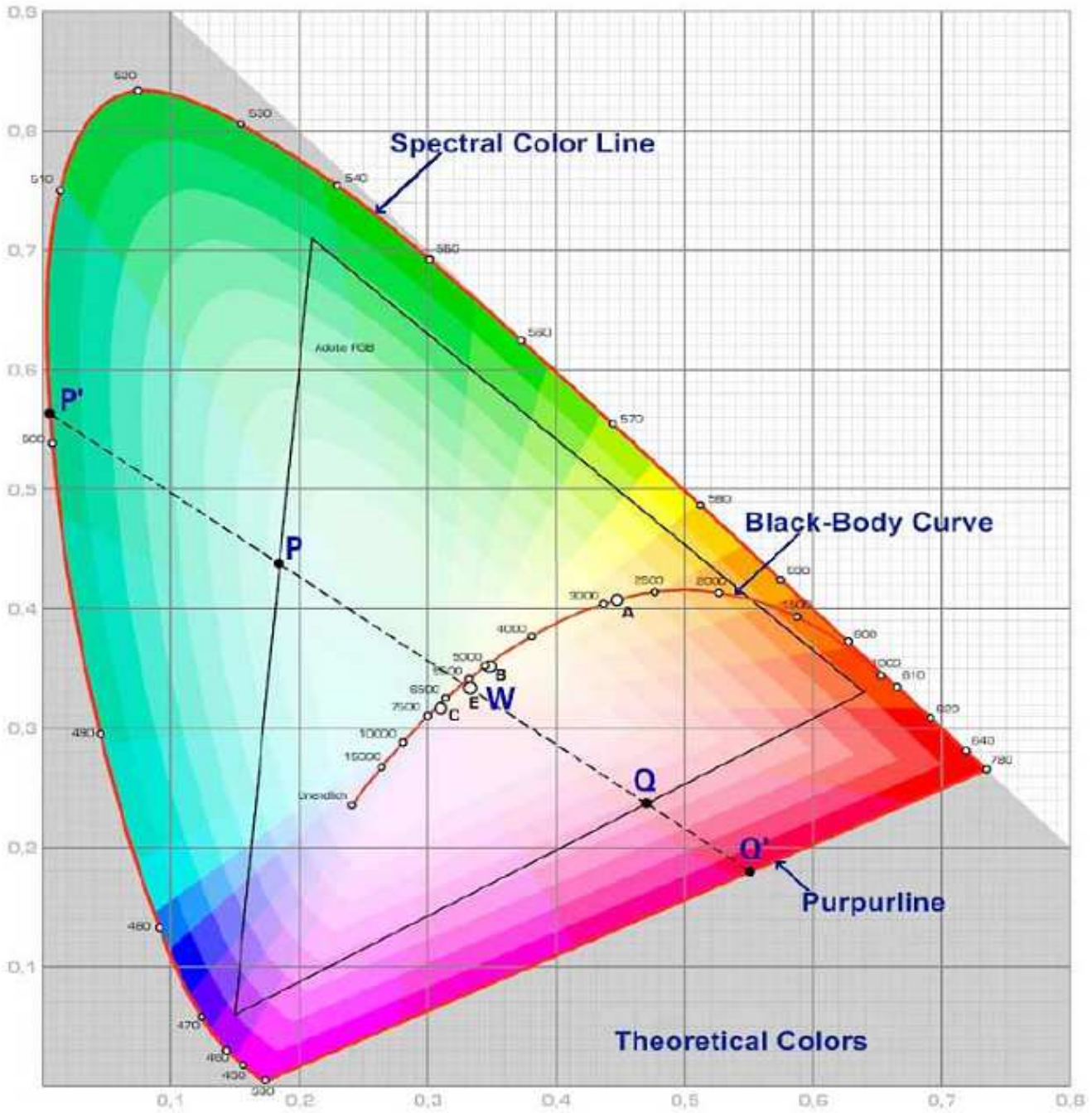   pick-and-place machine to insure precise pickup and avoid damage during production.

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